



FLIP CHIP MODULES TEST SPECS

TYPE: R 204
#009
QUADRUPLE FLIP-FLOP

3/1/66

TEST	CONDITIONS	MAXIMUM	MINIMUM
UPPER LEVEL	20MA LOAD TO -15 V	≤ 300 MV	≤ 300 MV
LOWER LEVEL	NO EXTERNAL LOAD	3.9 V	3.2 V
LOAD CURRENT	NO EXTERNAL LOAD	2.4 MA	1.8 MA
AC SENSITIVITY	HIGH FREQUENCY	+ 2.4 V	/
	LOW FREQUENCY	/	+ 0.6 V
TTT	RISE	≤ 135 NS	≤ 135 NS
	FALL	≤ 175 NS	≤ 175 NS
MARGINS	+ 10V	+ 10 V	- 10 V
	- 15V	+ 3.0 V	- V

DEC 30 1965



TECHNICAL INFORMATION

Instruction literature and technical bulletins are available on all digital products, if you would like to be added to our mailing list for this type of material or if you have any questions about the equipment you have purchased, please contact the nearest Digital Sales Office.

MAINTENANCE INFORMATION

Repair of printed circuitry should be done with a low voltage, fairly cool soldering iron to prevent damage to the transistors and keep the copper from lifting. Oscilloscopes used to troubleshoot a module or system should be grounded to prevent damaging transients.

9/21/66